



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20180807001
Qualification of TIPI as a new Assembly and Test Site for
Select LQFP Package Devices
Change Notification / Sample Request**

Date: August 30, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20180807001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.


DEVICE	CUSTOMER PART NUMBER
MSP430F1611IPM	null
MSP430F2418TPM	null
MSP430F1610IPM	null
MSP430F1611IPMR	null
MSP430F1612IPM	null
MSP430F2416TPM	null
MSP430F2417TPM	null
MSP430F2418TPMR	null
MSP430F2616TPM	null
MSP430F2617TPM	null
MSP430F2618TPM	null
MSP430F2618TPMR	null
MSP430F2619TPM	null
MSP430F4152IPMR	null
MSP430F2617TPMR	null
MSP430F2619TPMR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180807001		PCN Date:	Aug 30, 2018													
Title:	Qualification of TIPI as a new Assembly and Test Site for Select LQFP Package Devices																
Customer Contact:	PCN Manager		Dept:	Quality Services													
Proposed 1st Ship Date:	Nov 30, 2018		Estimated Sample Availability:	Date provided at sample request													
Change Type:																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process												
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site												
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the qualification of TIPI as a new Assembly and Test Site for Select LQFP Package Devices. Assembly differences are as follows:																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>TI Taiwan</td> <td>TAI</td> <td>TWN</td> <td>Chung Ho</td> </tr> <tr> <td>TI Philippines</td> <td>PHI</td> <td>PHL</td> <td>Baguio City</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City	TI Taiwan	TAI	TWN	Chung Ho	TI Philippines	PHI	PHL	Baguio City
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City														
TI Taiwan	TAI	TWN	Chung Ho														
TI Philippines	PHI	PHL	Baguio City														
Material differences:																	
<table border="1"> <thead> <tr> <th></th> <th>TI Taiwan</th> <th>TI Philippines (TIPI)</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>4042504</td> <td>4211470</td> </tr> <tr> <td>Mold Compound</td> <td>4205442</td> <td>4222198</td> </tr> </tbody> </table>							TI Taiwan	TI Philippines (TIPI)	Mount Compound	4042504	4211470	Mold Compound	4205442	4222198			
	TI Taiwan	TI Philippines (TIPI)															
Mount Compound	4042504	4211470															
Mold Compound	4205442	4222198															
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																	
Reason for Change:																	
Continuity of Supply																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.														
Changes to product identification resulting from this PCN:																	

Sample Product Shipping Label (not actual product label)

Assembly Site		
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI
TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI


TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL '2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

MSP430F1610IPM	MSP430F2416TPMR	MSP430F2616TPM	MSP430F2619TPMR
MSP430F1610IPMR	MSP430F2417TPM	MSP430F2616TPMR	MSP430F4132IPM
MSP430F1611IPM	MSP430F2417TPMR	MSP430F2617TPM	MSP430F4132IPMR
MSP430F1611IPMR	MSP430F2418TPM	MSP430F2617TPMR	MSP430F4152IPM
MSP430F1612IPM	MSP430F2418TPMR	MSP430F2618TPM	MSP430F4152IPMR
MSP430F1612IPMR	MSP430F2419TPM	MSP430F2618TPMR	
MSP430F2416TPM	MSP430F2419TPMR	MSP430F2619TPM	

Qualification Report
Qualification of TI-Philippines (TIPI) as Second Assembly Site for
MSP430F161x, F26xx, and F41xx
 Approval Date 01-Aug-2018

Product Attributes

Attributes	Qual Device: <u>MSP430F2618TPM</u>	QBS Package Reference: <u>MSP430F149IPM</u>	QBS Package Reference: <u>MSP430F249TPM</u>	QBS Package Reference: <u>PCI2250PGF</u>	QBS Package Reference: <u>TL16CP554APM</u>	QBS Package Reference: <u>TMS320F2803XAPN</u>
Assembly Site	TIPI	TIPI	TIPI	TIPI	TIPI	TIPI
Package Family	LQFP	LQFP	LQFP	LQFP	LQFP	LQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	TSMC-WF3	TSMC-WFT	TSMC-WFT	TSMC-TA1	DL-LIN	DMOS5
Wafer Fab Process	0.35UM-TSMC	0.35UM-TSMC	0.35UM-TSMC	0.35UM-TSMC	50C21	18F05

- QBS: Qual By Similarity
- Qual Device MSP430F2618TPM is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>MSP430F2618TPM</u>	QBS Package Reference: <u>MSP430F149IPM</u>	QBS Package Reference: <u>MSP430F249TPM</u>
AC	Autoclave 121C	96 Hours	1/77/0	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	-

Type	Test Name / Condition	Duration	QBS Package Reference: <u>PCI2250PGF</u>	QBS Package Reference: <u>TL16CP554APM</u>	QBS Package Reference: <u>TMS320F2803XAPN</u>
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	-
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	3/231/0

Preconditioning was performed for Autoclave, THB/Biased HAST, Temperature Cycle, and HTSL.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lscs/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com